

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Toshiki Hirano	10/07/2009
Haruhide Takahashi	10/08/2009
Shinobu Hagiya	10/08/2009
Shigenori Takada	10/08/2009
Kousaku Wakatsuki	10/09/2009
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Hitachi Global Storage Technologies Netherlands B.V.
<b>Street Address:</b>	Locatellikade 1
<b>Internal Address:</b>	Parnassustoren
<b>City:</b>	Amsterdam
<b>State/Country:</b>	NETHERLANDS
<b>Postal Code:</b>	1076 AZ
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12578754
<b>CORRESPONDENCE DATA</b>	
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CH \$40.00 12578754

**500988025**

**PATENT  
 REEL: 023369 FRAME: 0843**

NAME OF SUBMITTER:

Christopher J Brokaw

Total Attachments: 2

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## ASSIGNMENT FOR PATENT APPLICATION


Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

### Suspension for Protecting a Component from Mechanical Shock

Whereas, **Hitachi Global Storage Technologies Netherlands B.V.**, having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands (hereinafter referred to as "HITACHI"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature:  Date: 10/7/2009  
Typed Name: Toshiki Hirano
- 2) Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Typed Name: Haruhide Takahashi
- 3) Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Typed Name: Shinobu Hagiya
- 4) Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Typed Name: Shigenori Takada
- 5) Signature: \_\_\_\_\_ Date: \_\_\_\_\_  
Typed Name: Kousaku Wakatsuki

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### Suspension for Protecting a Component from Mechanical Shock

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Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed on the date(s) indicated beside my (our) signature(s).

- |    |  |                           |
|----|--|---------------------------|
| 1) | Signature: _____<br>Typed Name: Toshiki Hirano                         | Date: _____               |
| 2) | Signature: <u>Haruhide Takahashi</u><br>Typed Name: Haruhide Takahashi | Date: <u>Oct. 8, 2009</u> |
| 3) | Signature: <u>Shinobu Hagiya</u><br>Typed Name: Shinobu Hagiya         | Date: <u>Oct. 8, 2009</u> |
| 4) | Signature: <u>Shigenori Takada</u><br>Typed Name: Shigenori Takada     | Date: <u>Oct. 8, 2009</u> |
| 5) | Signature: <u>Kousaku Wakatsuki</u><br>Typed Name: Kousaku Wakatsuki   | Date: <u>Oct. 9, 2009</u> |